

TITLE OF INVENTION: ELECTRONIC-DEVICE-PROTECTING FILM,
ELECTRONIC-DEVICE-PROTECTING MEMBER, METHOD FOR
MANUFACTURING ELECTRONIC DEVICE, AND METHOD FOR
MANUFACTURING PACKAGE

ABSTRACT

The present invention provides: an electronic-device-protecting film used when semiconductor parts obtained by segmentation are to be sealed in the form of an array using a sealant after the semiconductor parts are rearranged, wherein the curing temperature of the sealant does not need to be adjusted downward; an electronic-device-protecting member; a method for manufacturing an electronic device; and a method for manufacturing a package. Specifically, provided is an electronic-device-protecting film 1 including a base layer 11 and an adhesive layer 12, which is used in a method including: bonding the adhesive layer 12 of the electronic-device-protecting film 1 to one surface 7a of a frame 7 having an opening 71, the adhesive layer 12 being bonded so as to cover the opening 71 of the frame 7; subsequently bonding a plurality of semiconductor parts to the surface 12a of the adhesive layer 12 that is exposed via the opening 71 with the semiconductor parts set apart from each other; subsequently covering the semiconductor parts and the surface 12a of the adhesive layer 12 with a sealant; and heat-curing the sealant to obtain an electronic device in which the semiconductor parts are sealed in an array configuration, wherein the ratio R_E of the tensile elastic modulus of the base layer 11 at 160°C to the tensile elastic modulus of the base layer 11 at 50°C is such that $0.05 < R_E < 1$.

[Fig. 2]